BFG325/XR

NPN 14 GHz wideband transistor

Rev. 2 — 15 September 2011 Product data sheet

1. Product profile

1.1 General description

NPN silicon planar epitaxial transistor in a 4-pin dual-emitter SOT143R plastic package.

1.2 Features and benefits

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures excellent reliability

1.3 Applications

- Intended for Radio Frequency (RF) front end applications in the GHz range, such as:
  - analog and digital cellular telephones
  - cordless telephones (Cordless Telephone (CT), Personal Communication Network (PCN), Digital Enhanced Cordless Telecommunications (DECT), etc.)
  - radar detectors
  - pagers
  - Satellite Antenna TeleVision (SATV) tuners
  - repeater amplifiers in fiber-optic systems

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{CBO}	collector-base voltage	open emitter		-	-	15	V
V_{CEO}	collector-emitter voltage	open base		-	-	6	V
I_C	collector current (DC)			-	-	35	mA
P_{tot}	total power dissipation	$T_{sp} \leq 90$ °C	[1]	-	-	210	mW
h_{FE}	DC current gain	I_C = 15 mA; V_{CE} = 3 V; T_j = 25 °C		60	100	200	
C_{CBS}	collector-base capacitance	V_{CB} = 5 V; f = 1 MHz; emitter grounded		-	0.26	0.4	pF
f_T	transition frequency	I_C = 15 mA; V_{CE} = 3 V; f = 1 GHz; T_{amb} = 25 °C		-	14	-	GHz

Table 1. Quick reference data *...continued*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
G_{max}	maximum power gain[2]	I_C = 15 mA; V_{CE} = 3 V; f = 1.8 GHz; T_{amb} = 25 °C	-	18.3	-	dB
$\|s_{21}\|^2$	insertion power gain	I_C = 15 mA; V_{CE} = 3 V; f = 1.8 GHz; T_{amb} = 25 °C; $Z_S = Z_L$ = 50 Ω	-	14	-	dB
NF	noise figure	$\Gamma_s = \Gamma_{opt}$; I_C = 3 mA; V_{CE} = 3 V; f = 2 GHz	-	1.1	-	dB

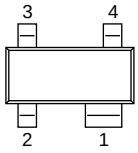
[1] T_{sp} is the temperature at the soldering point of the collector pin.

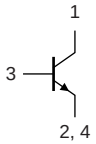
[2] G_{max} is the maximum power gain, if K > 1. If K < 1 then G_{max} = MSG, see Figure 4.

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	collector		
2	emitter		
3	base		
4	emitter		





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3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BFG325/XR	SC-61AA	plastic surface mounted package; reverse pinning; 4 leads	SOT143R

4. Marking

Table 4. Marking codes

Type number	Marking code[1]
BFG325/XR	S2*

[1] * = p: made in Hong Kong.

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter		-	15	V
V_{CEO}	collector-emitter voltage	open base		-	6	V
V_{EBO}	emitter-base voltage	open collector		-	2	V
I_C	collector current (DC)			-	35	mA
P_{tot}	total power dissipation	$T_{sp} \leq 90$ °C	[1]	-	210	mW
T_{stg}	storage temperature			–65	+175	°C
T_j	junction temperature			-	175	°C

[1] T_{sp} is the temperature at the soldering point of the collector pin.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point	$T_{sp} \leq 90$ °C	[1]	405	K/W

[1] T_{sp} is the temperature at the soldering point of the collector pin.

7. Characteristics

Table 7. Characteristics

T_j = 25 °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	I_E = 0 A; V_{CB} = 5 V	-	-	15	nA
h_{FE}	DC current gain	I_C = 15 mA; V_{CE} = 3 V	60	100	200	
C_{CBS}	collector-base capacitance	V_{CB} = 5 V; f = 1 MHz; emitter grounded	-	0.26	0.4	pF
C_{CES}	collector-emitter capacitance	V_{CE} = 5 V; f = 1 MHz; base grounded	-	0.27	-	pF
C_{EBS}	emitter-base capacitance	V_{EB} = 0.5 V; f = 1 MHz; collector grounded	-	0.53	-	pF
f_T	transition frequency	I_C = 15 mA; V_{CE} = 3 V; f = 1 GHz; T_{amb} = 25 °C	-	14	-	GHz
G_{max}	maximum power gain[1]	I_C = 15 mA; V_{CE} = 3 V; f = 1.8 GHz; T_{amb} = 25 °C	-	18.3	-	dB
$\lvert s_{21}\rvert^2$	insertion power gain	I_C = 15 mA; V_{CE} = 3 V; T_{amb} = 25 °C; $Z_S = Z_L$ = 50 Ω				
		f = 1.8 GHz	-	14	-	dB
		f = 3 GHz	-	10	-	dB
NF	noise figure	$\Gamma_s = \Gamma_{opt}$; I_C = 3 mA; V_{CE} = 3 V; f = 2 GHz	-	1.1	-	dB
$P_{L(1dB)}$	output power at 1 dB gain compression	I_C = 15 mA; V_{CE} = 3 V; f = 1.8 GHz; T_{amb} = 25 °C; $Z_S = Z_L$ = 50 Ω	-	8.7	-	dBm
IP3	third order intercept point	I_C = 15 mA; V_{CE} = 3 V; f = 1.8 GHz; T_{amb} = 25 °C; $Z_S = Z_L$ = 50 Ω	-	19.4	-	dBm

[1] G_{max} is the maximum power gain, if K > 1. If K < 1 then G_{max} = MSG, see Figure 4.

K is the Rollet stability factor: $K = \frac{1 + |Ds|^2 - |s_{11}|^2 - |s_{22}|^2}{2 \times |s_{21}| \times |s_{12}|}$ where $Ds = s_{11} \times s_{22} - s_{12} \times s_{21}$.

MSG = maximum stable gain.

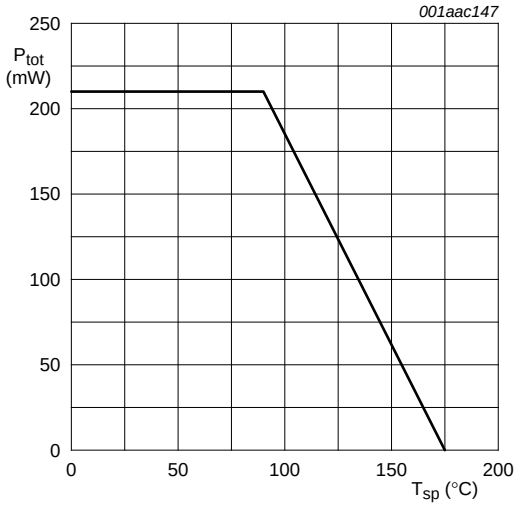


Fig 1. Power derating curve

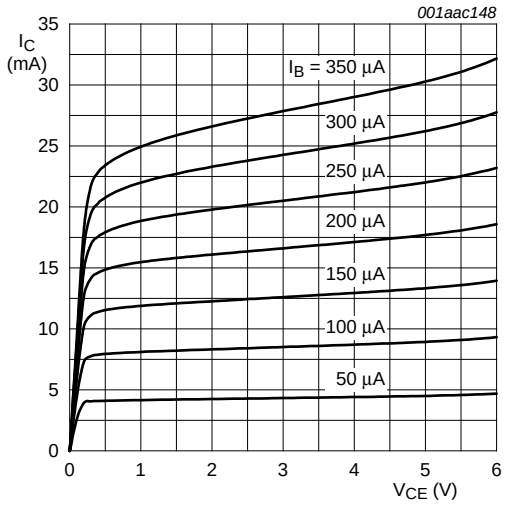
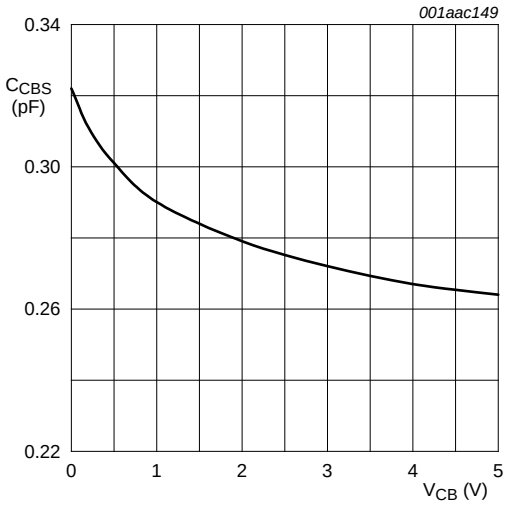
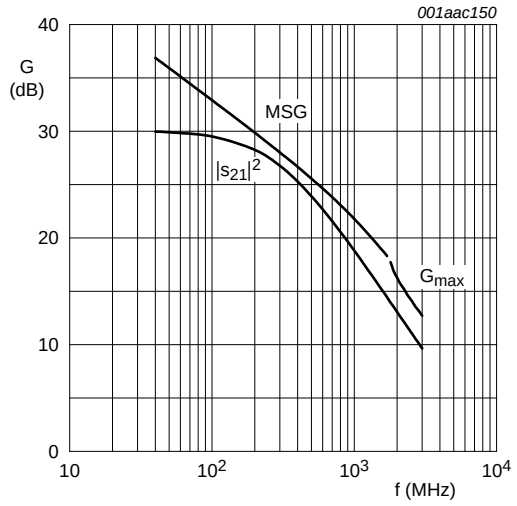


Fig 2. Collector current as a function of collector-emitter voltage; typical values



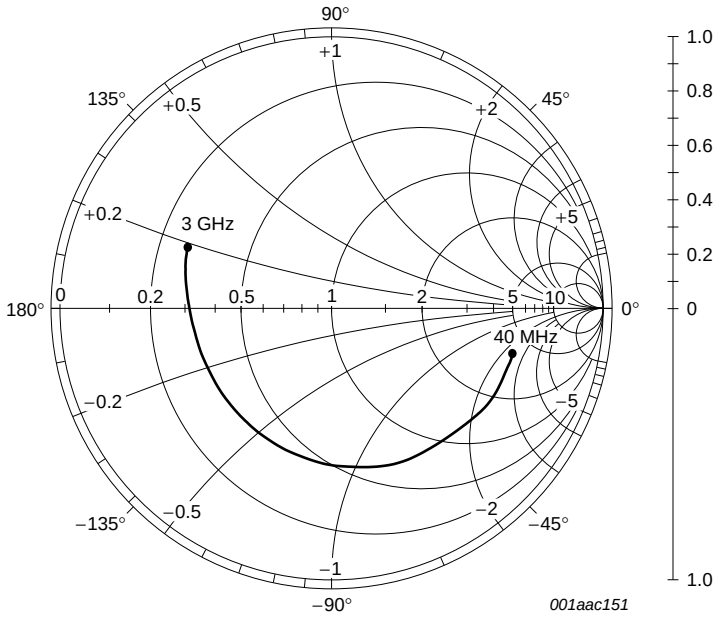
I_C = 0 mA; f = 1 MHz.

Fig 3. Collector-base capacitance as a function of collector-base voltage; typical values



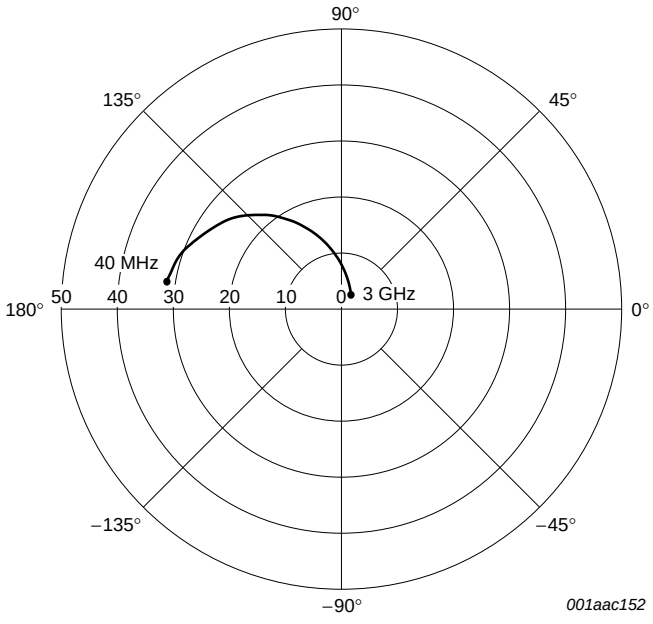
I_C = 15 mA; V_{CE} = 3 V.

Fig 4. Gain as a function of frequency; typical values



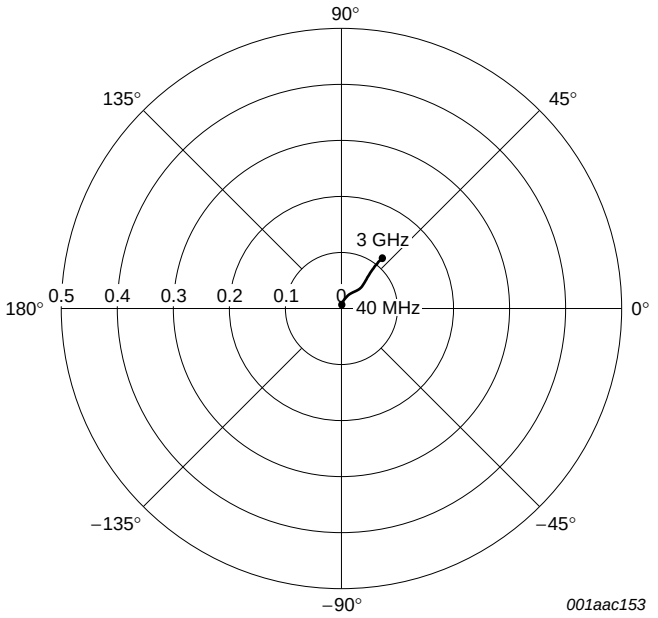
V_{CE} = 3 V; I_C = 15 mA; Z_o = 50 Ω.

Fig 5. Common emitter input reflection coefficient (s_{11}); typical values



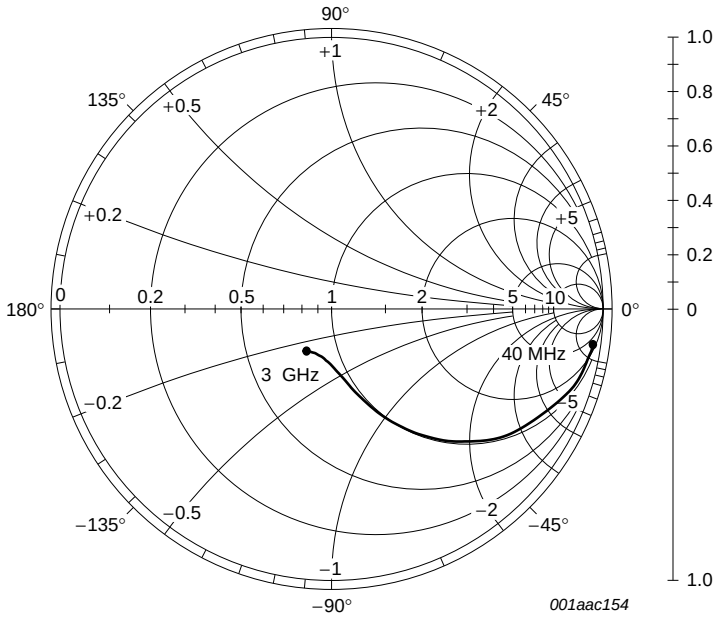
V_{CE} = 3 V; I_C = 15 mA.

Fig 6. Common emitter forward transmission coefficient (s_{21}); typical values



V_{CE} = 3 V; I_C = 15 mA.

Fig 7. Common emitter reverse transmission coefficient (s_{12}); typical values



V_{CE} = 3 V; I_C = 15 mA; Z_o = 50 Ω.

Fig 8. Common emitter output reflection coefficient (s_{22}); typical values

8. Application information

Table 8. SPICE parameters of the BFG325 DIE

Sequence	Parameter	Value	Unit
1	IS	26.6	aA
2	BF	200	-
3	NF	1	-
4	VAF	40	V
5	IKF	105	mA
6	ISE	2.3	fA
7	NE	2.114	-
8	BR	10	-
9	NR	1	-
10	VAR	2.5	V
11	IKR	10	A
12	ISC	0	aA
13	NC	1.5	-
14	RB	3.6	Ω
15	RE	1.5	Ω
16	RC	2.6	Ω
17	CJE	185.6	fF
18	VJE	890	mV
19	MJE	0.294	-
20	CJC	77.06	fF
21	VJC	601	mV
22	MJC	0.159	-
23	XCJC	1	-
24	FC	0.7	-
25	TF	8.1	ps
26	XTF	10	-
27	VTF	1000	V
28	ITF	150	mA
29	PTF	0	deg
30	TR	0	ns
31	KF	0	-
32	AF	1	-
33	TNOM	25	°C
34	EG	1.014	eV
35	XTB	0	-
36	XTI	8	-
37	Q1.AREA	2.5	-

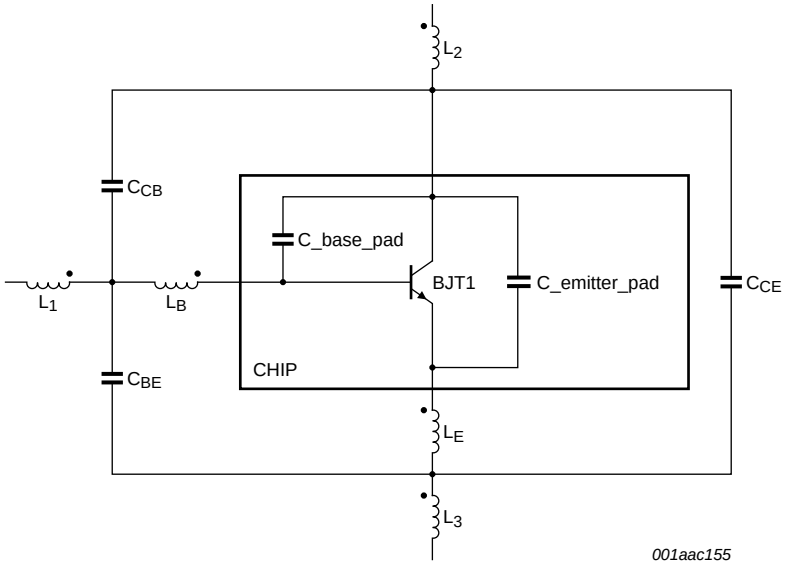


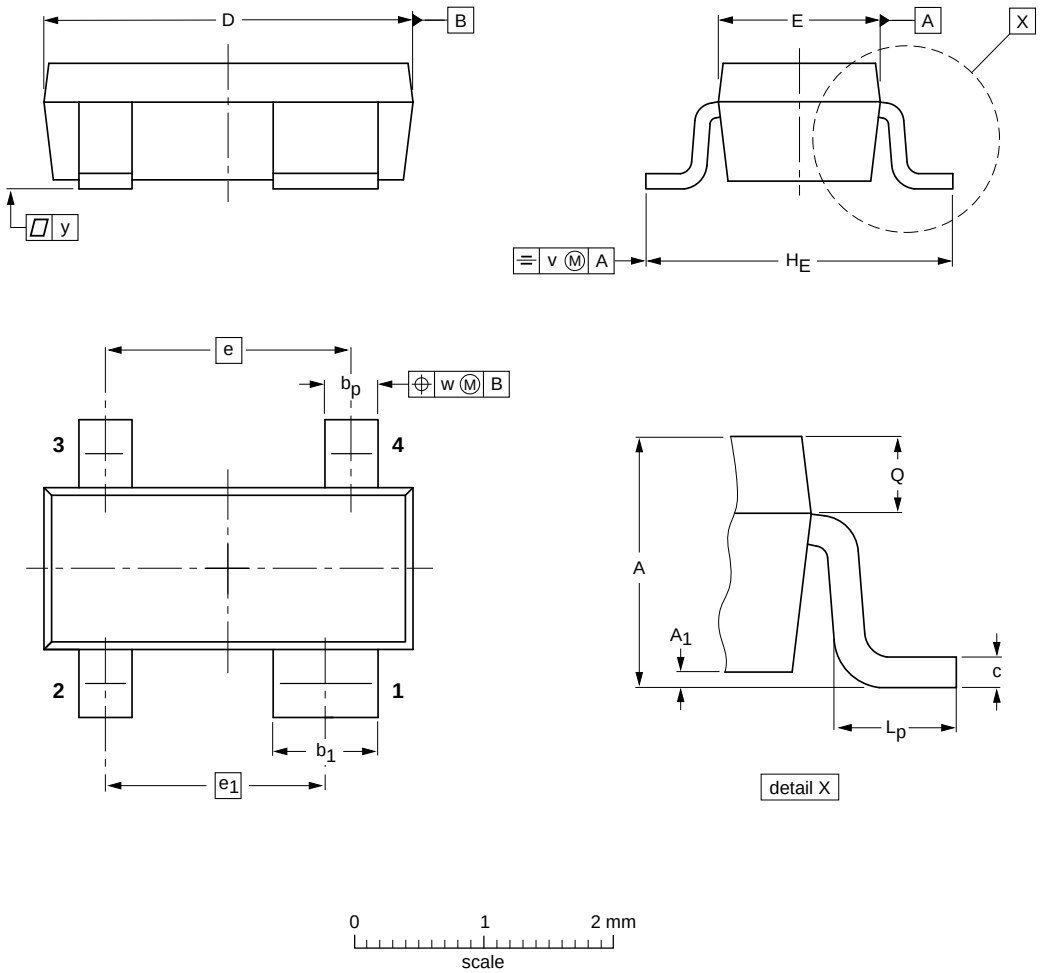
Fig 9. Package equivalent circuit of SOT143R

Table 9. List of components; see Figure 9

Designation	Value	Unit
C_{CB}	17	fF
C_{BE}	84	fF
C_{CE}	191	fF
C_base_pad	67	fF
C_emitter_pad	142	fF
L_B	0.95	nH
L_E	0.40	nH
L_1	0.12	nH
L_2	0.21	nH
L_3	0.06	nH

9. Package outline

Plastic surface-mounted package; reverse pinning; 4 leads **SOT143R**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	b_1	c	D	E	e	e_1	H_E	L_p	Q	v	w	y
mm	1.1 0.9	0.1	0.48 0.38	0.88 0.78	0.15 0.09	3.0 2.8	1.4 1.2	1.9	1.7	2.5 2.1	0.55 0.25	0.45 0.25	0.2	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT143R			SC-61AA			~~04-11-16~~ 06-03-16

Fig 10. Package outline SOT143R (SC-61AA)

10. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BFG325_XR v.2	20110915	Product data sheet	-	BFG325_XR v.1
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Package outline drawings have been updated to the latest version.			
BFG325_XR v.1 (9397 750 14247)	20050202	Product data sheet	-	-

11. Legal information

11.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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13. Contents

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